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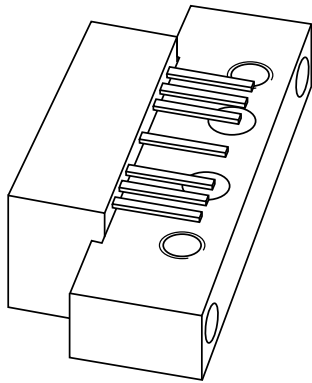
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



DATA SHEET



BGY687

**600 MHz, 21.5 dB gain push-pull
amplifier**

Product specification
Supersedes data of 1995 Sep 11

2001 Nov 08



600 MHz, 21.5 dB gain push-pull amplifier

BGY687

FEATURES

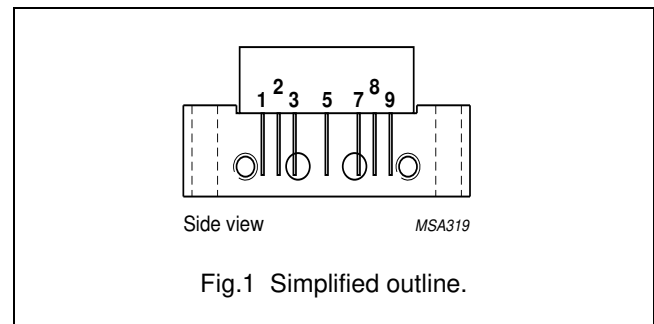
- Excellent linearity
- Extremely low noise
- Silicon nitride passivation
- Rugged construction
- Gold metallization ensures excellent reliability.

DESCRIPTION

Hybrid high dynamic range amplifier module designed for CATV systems operating over a frequency range of 40 to 600 MHz at a voltage supply of 24 V (DC).

PINNING - SOT115J

PIN	DESCRIPTION
1	input
2	common
3	common
5	+V _B
7	common
8	common
9	output



QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
G _p	power gain	f = 50 MHz	21	22	dB
		f = 600 MHz	22	–	dB
I _{tot}	total current consumption (DC)	V _B = 24 V	–	240	mA

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V _i	RF input voltage	–	65	dBmV
T _{stg}	storage temperature	–40	+100	°C
T _{mb}	operating mounting base temperature	–20	+100	°C

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CHARACTERISTICSBandwidth 40 to 600 MHz; $T_{\text{case}} = 30\text{ °C}$; $Z_S = Z_L = 75\ \Omega$.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
G _p	power gain	f = 50 MHz	21	22	dB
		f = 600 MHz	22	–	dB
SL	slope cable equivalent	f = 40 to 600 MHz	0.8	2.2	dB
FL	flatness of frequency response	f = 40 to 600 MHz	–	±0.2	dB
S ₁₁	input return losses	f = 40 to 80 MHz	20	–	dB
		f = 80 to 160 MHz	19	–	dB
		f = 160 to 600 MHz	18	–	dB
S ₂₂	output return losses	f = 40 to 80 MHz	20	–	dB
		f = 80 to 160 MHz	19	–	dB
		f = 160 to 550 MHz	18	–	dB
		f = 550 to 600 MHz	16	–	dB
S ₂₁	phase response	f = 50 MHz	–45	+45	deg
CTB	composite triple beat	85 channels flat; V _o = 44 dBmV; measured at 595.25 MHz	–	–54	dB
X _{mod}	cross modulation	85 channels flat; V _o = 44 dBmV; measured at 55.25 MHz	–	–54	dB
CSO	composite second order distortion	85 channels flat; V _o = 44 dBmV; measured at 596.5 MHz	–	–52	dB
d ₂	second order distortion	note 1	–	–66	dB
V _o	output voltage	d _{im} = –60 dB; note 2	58	–	dBmV
NF	noise figure	f = 600 MHz	–	6.5	dB
I _{tot}	total current consumption (DC)	note 3	–	240	mA

Notes

1. f_p = 55.25 MHz; V_p = 44 dBmV; f_q = 541.25 MHz; V_q = 44 dBmV; measured at f_p + f_q = 596.5 MHz.
2. f_p = 590.25 MHz; V_p = V_o; f_q = 597.25 MHz; V_q = V_o – 6 dB; f_r = 599.25 MHz; V_r = V_o – 6 dB; measured at f_p + f_q – f_r = 588.25 MHz.
3. The module normally operates at V_B = 24 V, but is able to withstand supply transients up to 30 V.

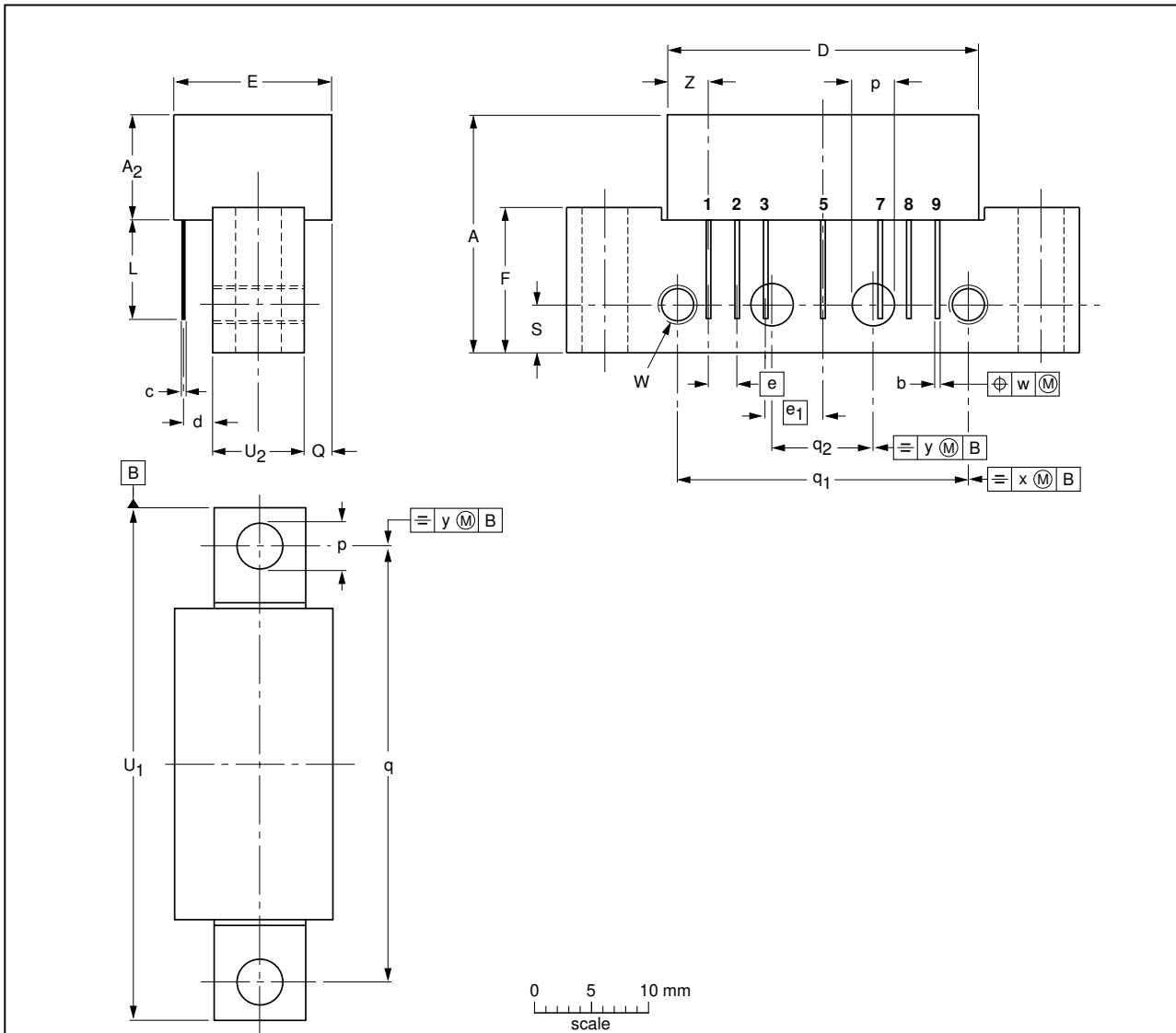
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PACKAGE OUTLINE

Rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 x 6-32 UNC and 2 extra horizontal mounting holes; 7 gold-plated in-line leads

SOT115J



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₂ max.	b	c	D max.	d	E max.	e	e ₁	F	L min.	p	Q max.	q	q ₁	q ₂	S	U ₁	U ₂	W	w	x	y	Z max.
mm	20.8	9.5	0.51 0.38	0.25	27.2	2.04 2.54	13.75	2.54	5.08	12.7	8.8	4.15 3.85	2.4	38.1	25.4	10.2	4.2	44.75 44.25	8.2 7.8	6-32 UNC	0.25	0.7	0.1	3.8

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT115J						04-02-04 10-06-18

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DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: <http://www.nxp.com>

For sales offices addresses send e-mail to: salesaddresses@nxp.com

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